

3LPG SC75-3-VB Datasheet P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (TYP.) (nC)			
	0.450 at V _{GS} = -4.5 V	-0.55				
-20	0.500 at V _{GS} = -2.5 V	-0.50	1			
	0.600 at V _{GS} = -1.8 V	-0.38				

FEATURES

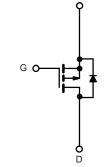
- Trench power MOSFET
- 100 % R tested
- Fast switching speed



APPLICATIONS

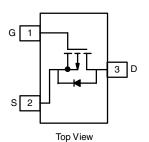
- Load / power switch for portable devices
- Drivers: relays, solenoids, displays
- Battery operated systems





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P-Channel MOSFET



ABSOLUTE MAXIMUM RATINGS ($T_A = 25 \degree C$, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	-20	V	
Gate-Source Voltage		V _{GS}	± 12	v	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C		-0.55 ^{b, c}		
	T _A = 70 °C	I _D	-0.45 ^{b, c}	A	
Pulsed Drain Current (t = 300 µs)		I _{DM}	-1.8	A	
Continuous Source-Drain Diode Current $T_A = 25 \text{ °C}$		I _S	-0.16 ^{b, c}		
Maximum Bower Dissinction	T _A = 25 °C	P	0.19 ^{b, c}	W	
Maximum Power Dissipation	T _A = 70 °C	P _D	0.12 ^{b, c}	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT		
Maximum Junction-to-Ambient ^{a, b}	t ≤ 5 s	R _{thJA}	440	530	°C/W	
Maximum Junction-to-Amblent %, ~	Steady State		540	650	0/00	

Notes

a. Maximum under steady state conditions is 650 °C/W.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 5 s.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static			1	I	1	1	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0, I _D = -250 μA	-20	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			-12	-	1//20	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	1.8	-	mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	-0.4	-	-1	V	
Gate-Source Leakage		$V_{DS} = 0 V, V_{GS} = \pm 8 V$	-	-	± 30		
	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 4.5 V$	-	-	± 1		
Zaus Oata Malta na Dusia Ouwant		$V_{DS} = -20 V, V_{GS} = 0 V$	-	-	-1	- μΑ	
Zero Gate Voltage Drain Current	IDSS	V_{DS} = -20 V, V_{GS} = 0 V, T_{J} = 85 °C	-	-	-10		
On-State Drain Current ^a	I _{D(on)}	V_{DS} = ≥ 5 V, V_{GS} = -4.5 V	-1.5	-	-	А	
		$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -0.4 \text{ A}$	-	0.450	-		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -0.2 \text{ A}$	-	0.500	-	Ω	
		$V_{GS} = -1.8 \text{ V}, \text{ I}_{D} = -0.1 \text{ A}$	-	0.600	-		
Forward Transconductance	g fs	$V_{DS} = -10 V, I_D = 0.4 A$	-	1	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	45	-	pF	
Output Capacitance	C _{oss}	V_{DS} = -10 V, V_{GS} = 0 V, f = 1 MHz	-	15	-		
Reverse Transfer Capacitance	C _{rss}		-	10	-		
Total Cata Charge	Qg	V_{DS} = -10 V, V_{GS} = -4.5 V, I_D = -0.4 A	-	1.65	2.50		
Total Gate Charge			-	1	2	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -0 \ V, \ V_{GS} = -2.5 \ V, \ I_D = -0.4$	-	0.2	-		
Gate-Drain Charge	Q _{gd}		-	0.26	-		
Gate Resistance	Rg	f = 1 MHz	2.4	12	24	Ω	
Turn-On Delay Time	t _{d(on)}		-	9	18		
Rise Time	t _r	V_{DD} = -10 V, R_L = 33.3 Ω	-	10	20		
Turn-Off DelayTime	t _{d(off)}	$I_D\cong$ -0.3 A, V_{GEN} = -4.5 V, R_g = 1 Ω	-	10	20		
Fall Time	t _f		-	8	16		
Turn-On Delay Time	t _{d(on)}		-	1	2	ns	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, \text{ R}_{L} = 33.3 \Omega$	-	8	16		
Turn-Off DelayTime	t _{d(off)}	$I_D\cong$ -0.3 A, V_{GEN} = -8 V, R_g = 1 Ω	-	9	18		
Fall Time	t _f		-	5	10		
Drain-Source Body Diode Characteris	tics						
Pulse Diode Forward Current ^a	I _{SM}		-	-	-1.5	А	
Body Diode Voltage	V _{SD}	I _S = -0.3 A	-	-0.8	-1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		-	16	24	ns	
Body Diode Reverse Recovery Charge	Q _{rr}		-	8	16	nC	
Reverse Recovery Fall Time	ta	I _F = -0.3 A, dI/dt = 100 A/μs	-	11	-		
Reverse Recovery Rise Time	t _b	1		5	-	ns	

Notes

a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$

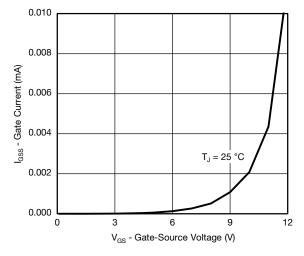
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

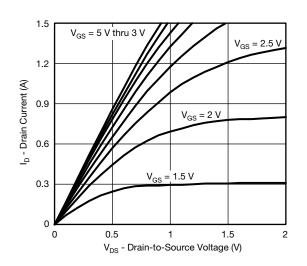
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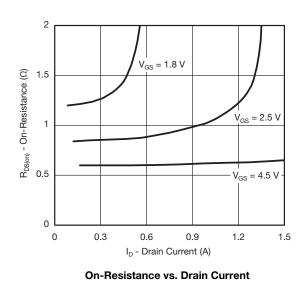
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

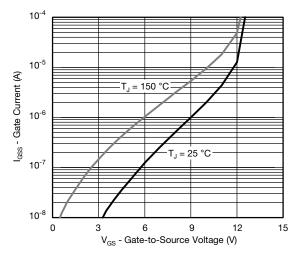


Gate Current vs. Gate-Source Voltage

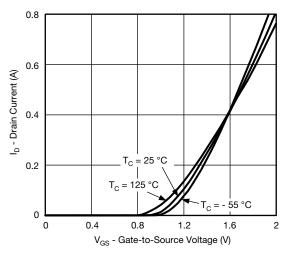


Output Characteristics

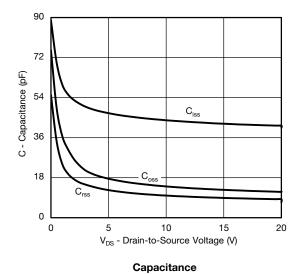




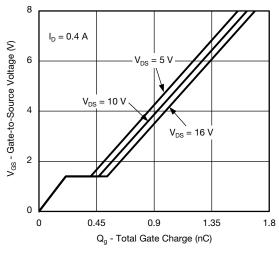
Gate Current vs. Gate-Source Voltage



Transfer Characteristics

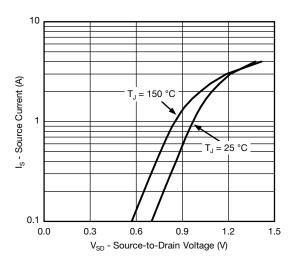




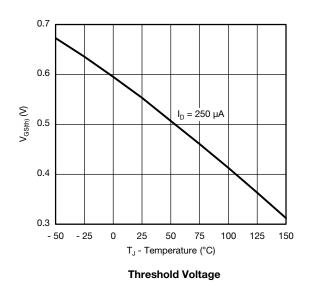


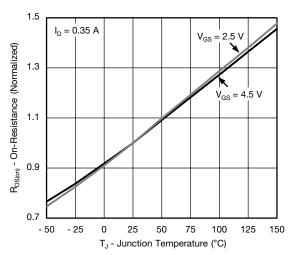
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



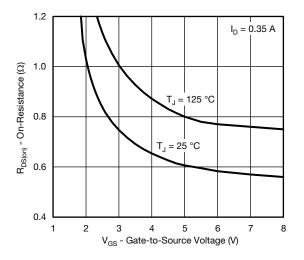


Source-Drain Diode Forward Voltage

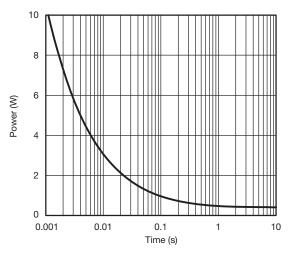


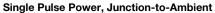


On-Resistance vs. Junction Temperature



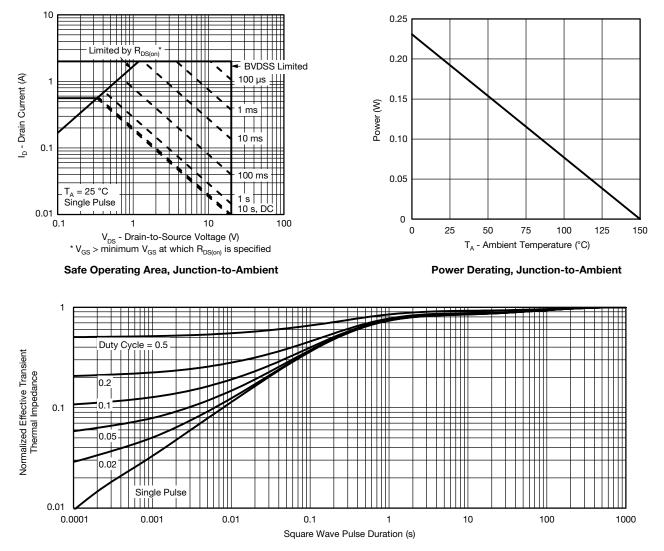
On-Resistance vs. Gate-to-Source Voltage







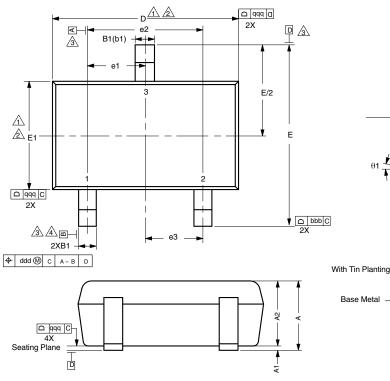


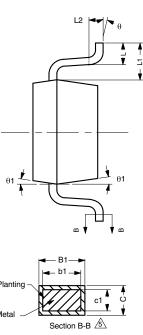


Normalized Thermal Transient Impedance, Junction-to-Ambient



SC-75: 3 Leads





DWG: 5868

Notes

Dimensions in millimeters will govern.

- Dimension D does not include mold flash, protrusions or gate burrs. Mold flash protrusions or gate burrs shall not exceed 0.10 mm per end. Dimension E1 does not include Interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.10 mm per side.
- 2. Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.

Datums A, B and D to be determined 0.10 mm from the lead tip. A Terminal positions are shown for reference only.

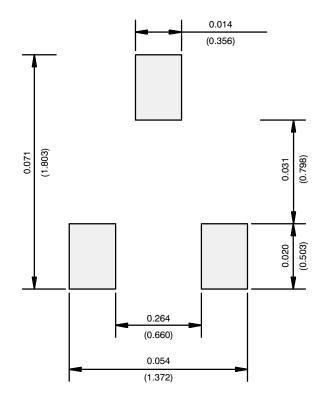
0.08 mm and 0.15 mm from the lead tip.

DIMENSIONS	TOLERANCES		
aaa	0.10		
bbb	0.10		
ccc	0.10		
ddd	0.10		

5.14					
DIM.	MIN. NOM. MAX.		MAX.	NOTE	
А	-	-	0.80		
A1	0.00	-	0.10		
A2	0.65	0.70	0.80		
B1	0.19	-	0.24	5	
b1	0.17	-	0.21		
с	0.13	-	0.15	5	
c1	0.10	-	0.12	5	
D	1.48	1.575	1.68	1, 2	
E	1.50	1.60	1.70		
E1	0.66	0.76	0.86	1, 2	
e1	0.50 BSC				
e2	1.00 BSC				
e3	0.50 BSC				
L	0.15	0.205	0.30		
L1	0.40 ref.				
L2	0.15 BSC				
q	0°	-	8°		
q1	4°	-	10°		



RECOMMENDED MINIMUM PADS FOR SC-75: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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